

What is claimed is:

1. A glass-encapsulated light-emitting diode, comprising:

an LED bare chip;

5 a pair of electrodes each connected to said LED bare chip on an opposite side thereof;

a pair of leads each connected to said electrode and thereby arranged for said LED bare chip to be interposed between said leads along an electrode direction; and

10 a pair of metallic member each connected to an other end of said lead, wherein said LED bare chip including said electrodes and at least a part of said leads are integrally encapsulated with glass to produce said glass-encapsulated light-emitting diode, and metallic members are separately
15 secured at both ends of said glass-encapsulated light-emitting diode.

2. The glass-encapsulated light-emitting diode according to claim 1, wherein each lead is designed not to
20 project out beyond said metallic member.

3. The glass-encapsulated light-emitting diode according to any one of claims 1-2, wherein glass for said glass-encapsulated light-emitting diode is composed of soft
25 glass.

4. The glass-encapsulated light-emitting diode according to any one of claims 1-3, wherein solder-plating is applied on at least both outermost sides of said glass-
30 encapsulated light-emitting diode in an extending direction of said pair of leads.